Roll	No	Total Printed Pages : 3
Г	07	BEC104
B	TECH (ELECTR	ONIC & COMM. ENGG.)
	VII SEM Exa	mination, Dec2017
		TECHNOLOGY
Time:	: 3 Hours]	[Total Marks 60
17,120,17,17,03		oporting material is permitted during
1.	Nil	Nil
Note:	1. Attempt any fix from each unit.	ve questions selecting one question
	2. Each question co	arry equal marks.
		UNIT-I
1, /	What is float-zone Czocharlski groth? V for float-zone groth.	growth? How it is different from What are the different king of doping
		OR

- Explain the different type of crystal defects.
- What do you understand by metallurgical grade silicon and electronic grade silicon? What are different steps for production of EGS from MGS.

### UNITH

w epitaxial layer. Explain one method for determine dopant profile in profile obtained by ion- implantation during MBE groth. What is MBE? Compare it with CVD. Draw the doping

Describe atmospheric pressure CVD for dielectric in detail. What is the major drawback of APCVD and how it is

# UNIT-III

- diagram. Discuss reactive Ion etching ( RIE) with the help of
- What is photoresist? What are its basic kind? What requirement a photoresist most full fill.

6 diagram of mask generation, Explain any one type of printer. Explain all the lithography steps in detail. Draw a flow

OR.

## AI-LIND

cross-sectional views for CMOS inverter using N-well Explain the fabrication process steps along with vertical

7.

### OR.

What do you mean by class of a clean room? Give the steps in a standard RCA cycle during water cleaning.

### UNIT-V

- Write a short notes on any three:
- (4x3=12)

- a) SOI
- b) Locos
- c) Metallization
- d) Planarization

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Contd.

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